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*** PRODUCT SPECIFICATION FOR PCB MANUFACTURING ***

PRODUCT OWNER : *** ATMEL Norway AS ***
DOCUMENT : A0608.3.1000.C
DATE : 2007-06-26
REVISION : C

PREPARED BY :
BOARD WIDTH : 100.0 mm
BOARD HEIGHT : 100.0 mm
BOARD THICKNESS : 1.6 mm +/- 10%
NO OF LAYERS : 4
MATERIAL : Glass Epoxy FR-4, NEMA class 2, UL 94V-0, Tg minimum 130 C
Materials in compliance with the RoHS and WEEE directives
MARKINGS: Logo, Week/Year, UL
QUALITY REQUIREMENTS: IPC-A-600 Class 2, IPC-6010 Series (current revisions),
and all other relevant IPC specifications.
COPPER THK. : Cu-thickness outer layers: 35 um finished brd.
COPPER (INNER) : Cu-thickness inner layers : 35 um
COPPER PASSIVATION : ENIG (to meet IPC requirements)
RESIST MASK : Photo polymer Wet film (to meet IPC requirements)
VIA-HOLES : Via-holes TENTED (OVERPRINTED, NOT PLUGGED)
LEGEND COLOUR : Silk screen colour: WHITE
LEGEND ON LAYER(S) : Silk screen legend: PRIMARY SIDE
TECHNOLOGY (TOP) : SMD Primary side
Cu TRACK/TRACE : Minimum conductor width : 0.33 mm (13 mils)
Cu SPACING : Minimum conductor spacing: 0.15 mm (6 mils)
MINIMUM VIA : Minimum via-pad diameter : 0.66 mm (26 mils)
Min via hole (SEE HOLE INFORMATION FURTHER DOWN)
Min via hole may have more than one pad diameter.
TEST : Electrical Test

HOLE INFORMATION:
Tolerances +/- 0.1 mm, unless specified otherwise.

PLATED HOLES:

T1 VH DIA = 0.3 mm QTY = 251 (VIA-HOLES)
T2 PTH DIA = 1.0 mm QTY = 139
T3 PTH DIA = 1.4 mm QTY = 28

NON-PLATED HOLES:

T4 NP DIA = 1.6 mm QTY = 1
T5 NP DIA = 1.8 mm QTY = 1
T6 NP DIA = 3.2 mm QTY = 4